

MOSFET Maximum Ratings T_J = 25°C unless otherwise noted.

Symbol	Parameter		Ratings	Units	
V _{DSS}	Drain-to-Source Voltage	40	V		
V _{GS}	Gate-to-Source Voltage		±20	V	
	Drain Current - Continuous (V _{GS} =10) (Note 1)	T _C =25°C	80		
I _D	Pulsed Drain Current	T _C = 25°C	See Figure 4	— A	
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	70	mJ	
P _D	Power Dissipation		94	W	
	Derate Above 25°C		0.63	W/ºC	
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C	
$R_{\theta JC}$	Thermal Resistance, Junction to Case		1.6	°C/W	
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	43	°C/W	

Notes:

1: Current is limited by bondwire configuration.

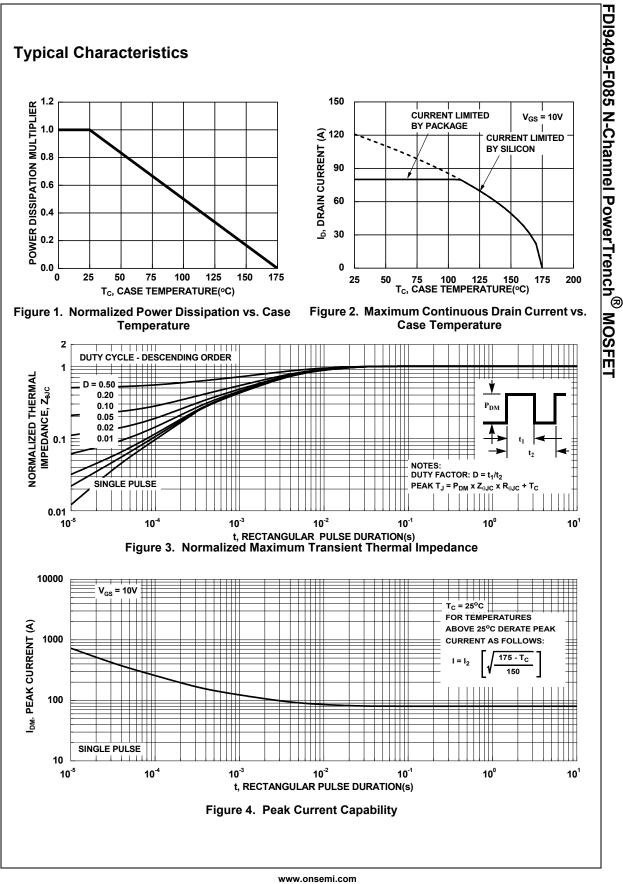
2: Starting $T_J = 25^{\circ}$ C, L = 34uH, $I_{AS} = 64$ A, $V_{DD} = 40$ V during inductor charging and $V_{DD} = 0$ V during time in avalanche.

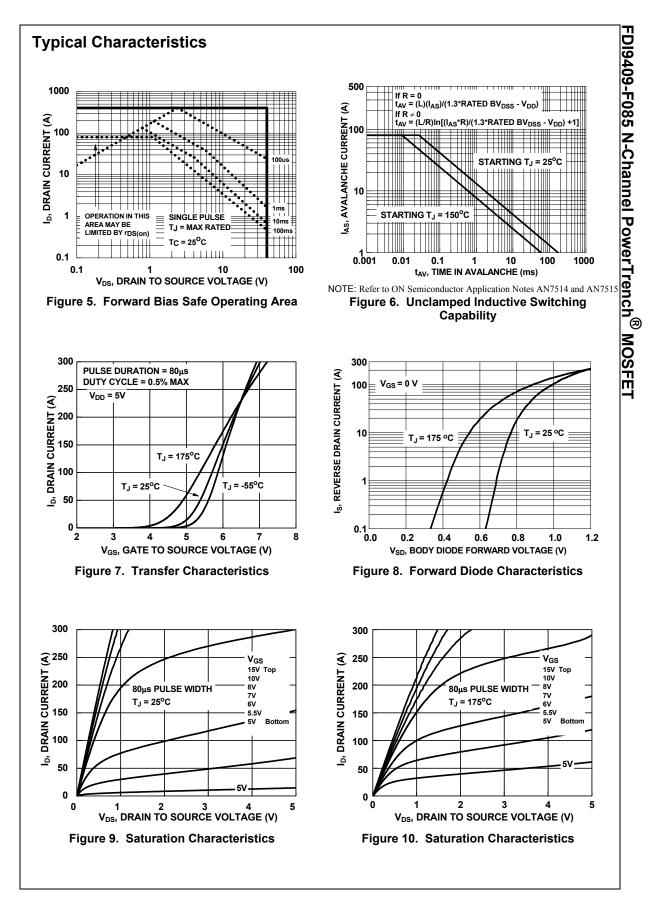
3: R_{0JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0JC} is guaranteed by design, while R_{0JA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

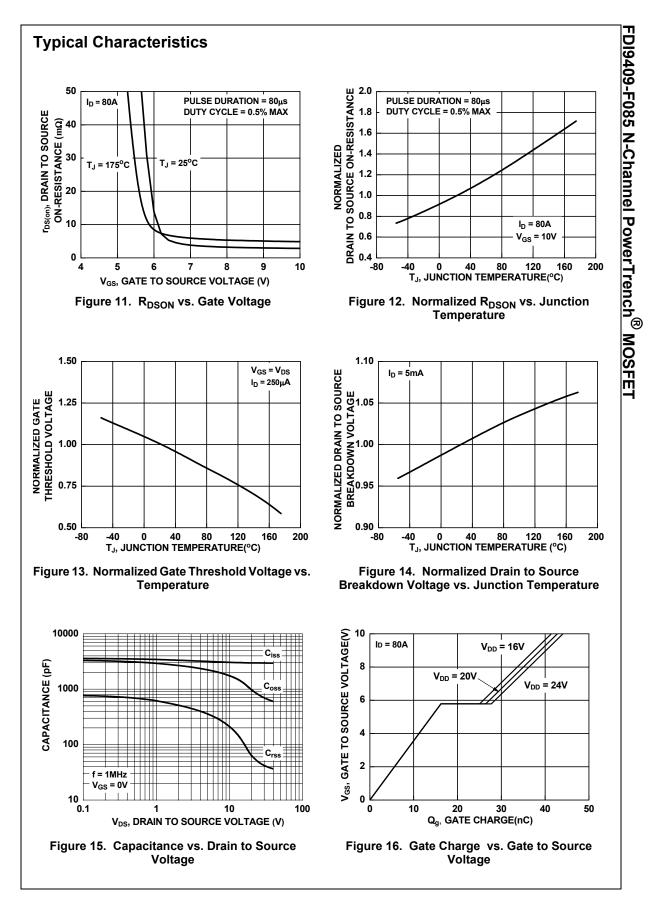
Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDI9409	FDI9409-F085	TO-262	Tube	N/A	50 units

Symbol	Parameter	Test Conditions			Min.	Тур.	Max.	Units
Off Cha	racteristics	,						
B _{VDSS}	Drain-to-Source Breakdown Voltage	I _D = 250μA,	$V_{GS} = 0$	V	40	-	-	V
	Drain-to-Source Leakage Current	$V_{\rm DS}$ =40V, $T_{\rm J}$ = 25°C			-	-	1	μA
IDSS					-	-	1	mA
I _{GSS}	Gate-to-Source Leakage Current	$V_{GS} = \pm 20V$		-	-	±100	nA	
On Cha	racteristics							
V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$	/ _{GS} = V _{DS} , I _D = 250μA		2.0	3.0	4.0	V
_		I _D = 80A,	$T_J = 25^{\circ}C$		-	2.9	3.8	mΩ
R _{DS(on)}	Drain to Source On Resistance	V _{GS} = 10V	T _J = 1	75°C (Note 4)	-	4.9	6.4	mΩ
Dynami	ic Characteristics							
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0V, f = 1MHz			-	2980	-	pF
C _{oss}	Output Capacitance				-	788	-	pF
C _{rss}	Reverse Transfer Capacitance			-	45	-	pF	
Rg	Gate Resistance	f = 1MHz		-	2.2	-	Ω	
Q _{g(ToT)}	Total Gate Charge at 10V	$V_{GS} = 0 \text{ to } 10V \qquad V_{DD} = 32V \\ V_{GS} = 0 \text{ to } 2V \qquad I_D = 80A \\ \hline \\ - \\ - \\ - \\ - \\ - \\ - \\ - \\ - \\ -$		-	43	56	nC	
Q _{g(th)}	Threshold Gate Charge			-	5	7	nC	
Q _{gs}	Gate-to-Source Gate Charge			-	15.5	-	nC	
Q _{gd}	Gate-to-Drain "Miller" Charge			-	10	-	nC	
Switchi	ng Characteristics							
t _{on}	Turn-On Time				-	-	193	ns
t _{d(on)}	Turn-On Delay	V _{DD} = 20V, I _D = 80A,		-	17	-	ns	
t _r	Rise Time			-	90	-	ns	
t _{d(off)}	Turn-Off Delay	V_{GS} = 10V, R_{GEN} = 6 Ω			-	24	-	ns
t _f	Fall Time			-	10	-	ns	
t _{off}	Turn-Off Time			-	-	50	ns	
	ource Diode Characteristics							
Drain-S		I _{SD} =80A, V _{GS} = 0V		/	-	-	1.25	V
	Source to Drain Diade Voltage	I _{SD} = 40A, V _{GS} = 0V			-	-	1.2	V
	Source-to-Drain Diode Voltage		$V_{\rm GS} = 0$	v				
Drain-S V _{SD} t _{rr}	Source-to-Drain Diode Voltage Reverse-Recovery Time				-	54	71	ns







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